

SPECIFICATION FOR APPROVAL

承 認 書

Description : Piezo Audio Indicator

Kingstate Part No. : KMIG1240H-TR

Customer's Model No. : _____

Specification No. : PKD-9141

Number Of The Edition : 1.4

CUSTOMER'S APPROVED SIGNATURE		





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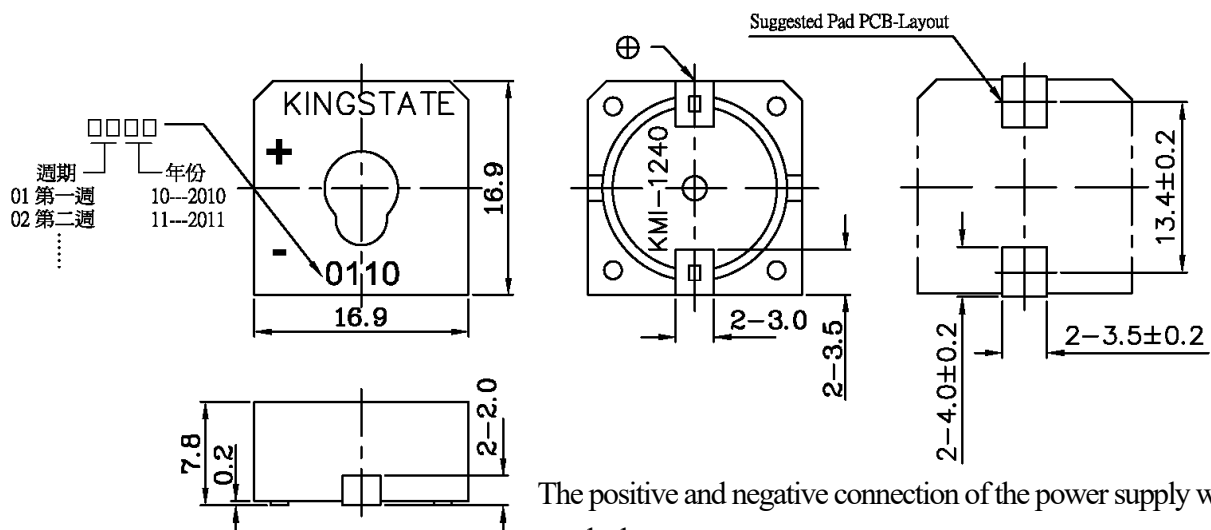
A. SCOPE 範疇

This specification applies piezo audio indicator, **KMIG1240H-TR**
 此規格書適用於壓電式蜂鳴器, **KMIG1240H-TR**

B. SPECIFICATION 規格

No.	Item	Unit	Specification	Condition
1	Resonant frequency 共振頻率	KHz	4.0±0.2	
2	Operating Volt. range 操作電壓範圍	VDC	3~16	
3	Current consumption 消耗電流	mA	MAX 18	at 12VDC
4	Sound pressure level 輸出音壓	dB	MIN 90	at 10cm/12VDC
5	Rated Voltage 額定電壓	VDC	12	
6	Tone 聲音		Continuous 直音	
7	Operating temp. 操作溫度	°C	-30~+70	
8	Storage temp. 儲存溫度	°C	-40~+80	
9	Dimension 尺寸	mm	L16.9 x W16.9 x H7.8	See appearance drawing 請參照外觀尺寸圖
10	Weight (MAX) 重量	gram	3.2	
11	Material 材質		PPS UL-94 V-0 (BLACK)	
12	Terminal 端子		SMD type	See appearance drawing 請參照外觀尺寸圖
13	Environmental Protection Regulation 環保法規		ROHS 2.0	
14	Moisture sensitive level 濕敏等級	Class	5	Less than or equal to 30°C/60%RH, 48 hours of Floor life. 小於或等於 30°C/60%RH 48 小時車間壽命

C. APPEARANCE DRAWING 外觀尺寸圖

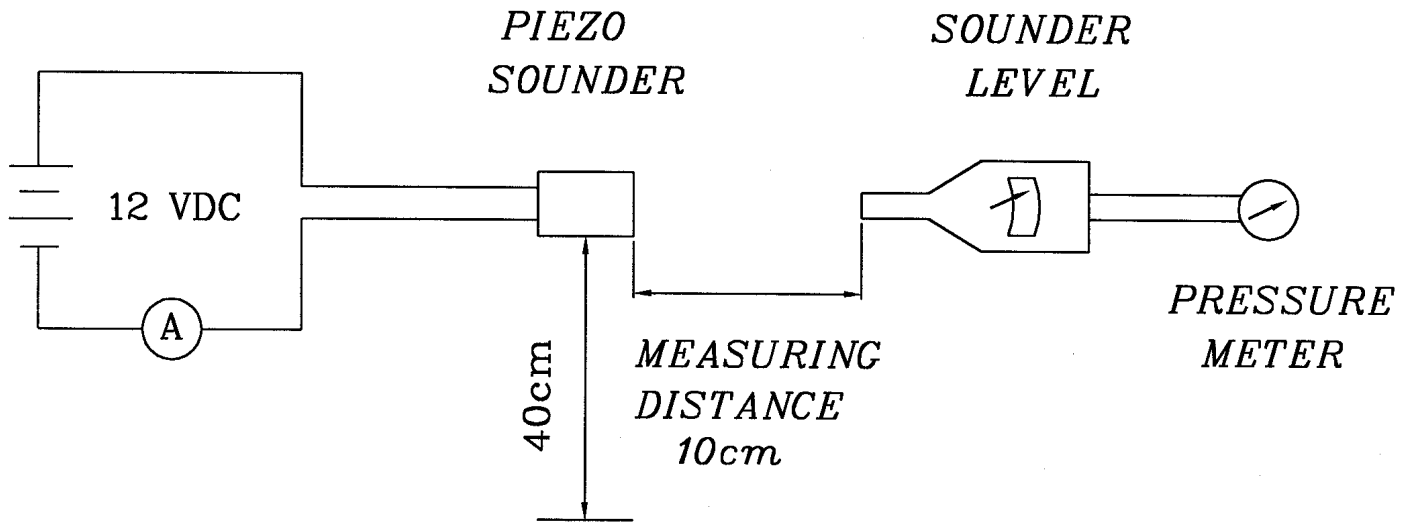


Tol : ± 0.5 Unit : mm

The positive and negative connection of the power supply will burn out the buzzer
 電源正負極接反會燒壞蜂鳴器

D. MEASURING METHOD 測量方法

S.P.L. Measuring Circuit 音壓測試接線圖



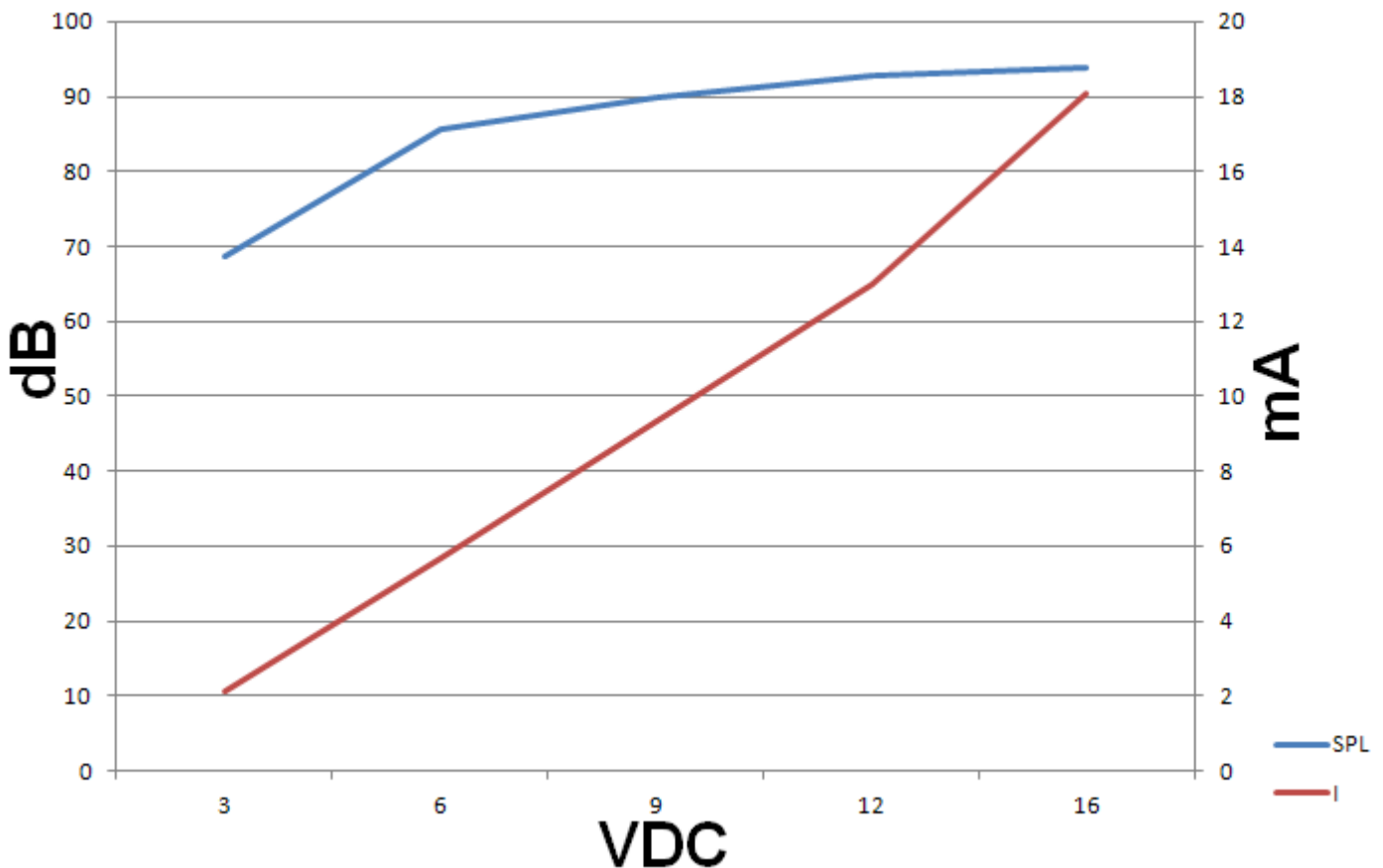
Mic : RION S.P.L meter UC30 or equivalent

Mic : RION 噪音計 UC30 或同等品

S.G : Hewlett Packard 33120A Function Generator or equivalent

S.G : Hewlett Packard 33120A 函數信號產生器或同等品

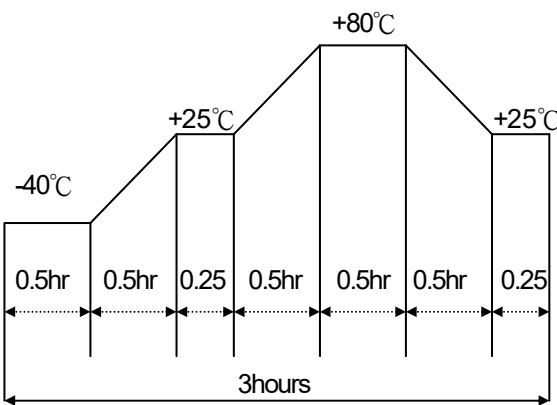
E. VOLTAGE: SOUND PRESSURE LEVEL / VOLTAGE: CURRENT CONSUMPTION CHARACTERISTICS 電壓與音壓/電壓與耗電流之特性



F. MECHANICAL CHARACTERISTICS 機械特性

No.	Item	Test Condition	Evaluation standard
1	Solderability 焊錫附著性	Lead terminals are immersed in solder bath of $+260\pm 5^{\circ}\text{C}$ for 3 ± 1 second. 端子置於錫膏內,錫膏溫度: $+260\pm 5^{\circ}\text{C}$. 焊接時間: 3 ± 1 秒.	95% surface of lead pads must be covered with fresh solder 錫膏須覆蓋端子上方 95%
2	Soldering Heat Resistance 焊錫耐熱性	Lead terminal are immersed in soldering bath of $+360\pm 10^{\circ}\text{C}$ for 3 ± 0.5 second. 端子部份浸入以 $+360\pm 10^{\circ}\text{C}$ 焊錫槽 3 ± 0.5 秒	No interference in operation. 操作上無任何不良.
3	Terminal Mechanical Strength 端子強度	2 lead pads shall be soldered on the pc board, and the force (10n) shall be applied behind the part for 10 ± 1 seconds. 將 2 個端子焊在 PC 板上後,對單體施以 10n 拉力 10 ± 1 秒	No damage and cutting off 端子不鬆動, 不脫落
4	Vibration 振動試驗	Buzzer shall be measured after being applied vibration of amplitude of 1.5mm with 10 to 55hz band of vibration frequency to each of 3 per-pendicular directions for 2 hours. 振動週波數 10~55HZ、全振幅 1.5mm 於 X.Y.Z 3 個方向,各 2 小時.	The value of oscillation frequency/ current consumption should be in $\pm 10\%$ compared with initial ones .The SPL should be in $\pm 10\text{dB}$ compared with initial one. 諧振頻率與消耗電流變化量須在 $\pm 10\%$ 內. 輸出音壓變化量須在 $\pm 10\text{dB}$ 內.
5	Drop test 落下測試	The part only shall be dropped from a height of 75cm onto a 40mm thick wooden board 3 times in 3 axes (X.Y.Z). (a total of 9 times). 單體從 75 公分高處, X.Y.Z.3 個方向,各 3 回,落於 40mm 厚木板上.	

G. ENVIRONMENT TEST 環境測試

No.	Item	Test Condition	Evaluation standard
1	High temp. test 高溫測試	After being placed in a chamber at $+80^{\circ}\text{C}$ for 240 hours 置於 $+80^{\circ}\text{C}$ 環境中 72 小時	Being placed for 4 hours at $+25^{\circ}\text{C}$, buzzer shall be measured. The value of oscillation frequency/ current consumption should be in $\pm 10\%$ compared with initial ones .The SPL should be in $\pm 10\text{dB}$ compared with initial one. 經測試後, 靜置於 $+25^{\circ}\text{C}$ (室溫) 環境中 4 小時後,諧振頻率與消耗電流變化量須在 $\pm 10\%$ 內. 輸出音壓變化量須在 $\pm 10\text{dB}$ 內.
2	Low temp. test 低溫測試	After being placed in a chamber at -40°C for 240 hours 置於 -40°C 環境中 72 小時	
3	Humidity test 相對濕度測試	After being placed in a chamber at $+40^{\circ}\text{C}$ and $90\pm 5\%$ relative humidity for 240 hours 置於 $+40^{\circ}\text{C}$, 相對濕度 $90\pm 5\%$ 環境中 72 小時	
4	Temp. cycle test 溫度循環試驗	The part shall be subjected to 5 cycles. One cycle shall be consist of: 單體承受溫度循環測試 5 次,其循環內容如圖示: 	

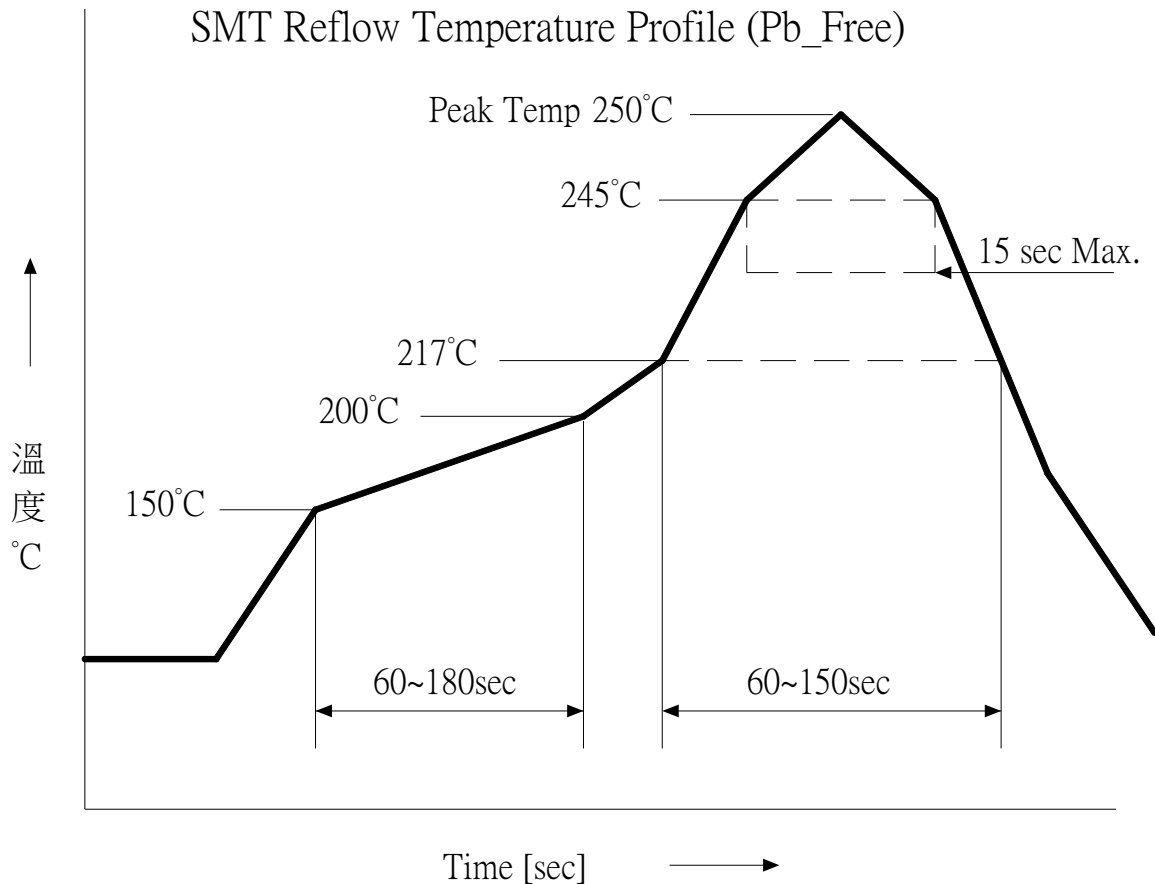
H. RELIABILITY TEST 信賴性測試

No.	Item	Test condition	Evaluation standard
1	Operating life test 壽命測試	1. Continuous life test 高溫壽命測試(連續) 48 hours continuous operation at +55°C with DC 12V applied. 在+55°C環境下,以 DC 12V 電壓連續操作 48 小時 2. Intermittent life test 室溫壽命測試(間歇) A duty cycle of 1 minute on, 1 minutes off, a minimum of 5,000 times at room temp. (+25±2°C) and DC12V applied 在室溫下(+25±2°C), 以 DC 12V 電壓操作, 通電 1 分鐘/斷電 1 分鐘, 測試 5,000 次循環。	Being placed for 4 hours at +25°C, buzzer shall be measured. The value of oscillation frequency/ current consumption should be in ±10% compared with initial ones .The SPL should be in ±10dB compared with initial one. 經測試後, 靜置於+25°C (室溫) 環境中 4 小時後, 諧振頻率與消耗電流變化量須在±10%內. 輸出音壓變化量須在±10dB 內。

TEST CONDITION.

Standard Test Condition	:	a) Temperature : +5 ~ +35°C	b) Humidity : 45-85%	c) Pressure : 860-1060mbar
一般測試條件	:	a) 溫度 : +5 ~ +35°C	b) 濕度 : 45-85%	c) 氣壓 : 860-1060mbar
Judgement Test Condition	:	a) Temperature : +25 ± 2°C	b) Humidity : 60-70%	c) Pressure : 860-1060mbar
爭議時測試條件	:	a) 溫度 : +25 ± 2°C	b) 濕度 : 60-70%	c) 氣壓 : 860-1060mbar

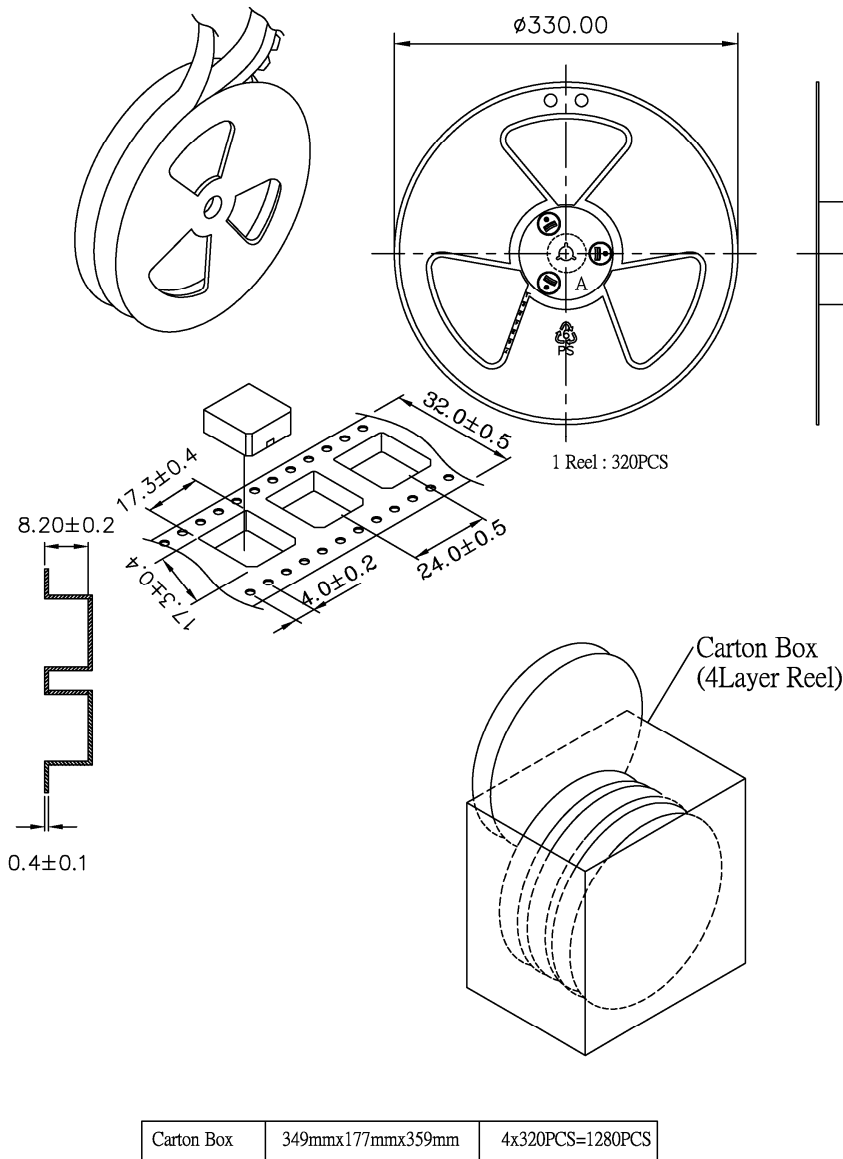
I. Recommended Temperature Profile For Reflow Oven 建議迴焊爐溫度曲線



Note: 245°C is Less than 15 sec. ,but only pass the lead free reflow once.

備注: 245°C不可超過 15 秒, 且只能過無鉛迴流焊一次。

J. PACKING STANDARD 包裝規格



防潮卡位置
Moisture card position

Caution
This bag contains
MOISTURE-SENSITIVE DEVICES

LEVEL **5**

- Calculated shelf life in sealed bag: 12 months at <math><40^{\circ}\text{C}</math> and <math><90\%</math> relative humidity(RH)
- Peak package body temperature: **+80** °C
- After bag is opened, devices that will be subjected to reflow solder or other high temperature process must be
 - Mounted within: **48** hours of factory conditions
≤30°C/60% RH, or
 - Stored per J-STD-033
- Devices require bake, before mounting, if:
 - Humidity Indicator Card reads >10% for level 2a-5a devices or >60% for level 2 devices when read at 23±5°C
 - 3a or 3b are not met
- If baking is required, refer to IPC/JEDEC J-STD-033 for bake procedure

Bag Seal Date: _____

Note: Level and body temperature defined by IPC/JEDEC J-STD-020

Date	PRC	QTY	P/N	INITIAL

Packing requirements:

包裝要求:

- Apply drying treatment before packing the product
产品装袋前干燥处理
- Vacuum package by MBB
使用 MBB 包装袋真空包装
- Add desiccant
加入去湿剂
- Add moisture indication card
加入防潮標示卡